

SVxx16xxQ series

16 Amp High Junction Temperature SCRs

Absolute Maximum Ratings – Standard SCRs

Symbol	Parameter	Test Conditions	Value	Unit
V_{DSM}/V_{RSM}	Peak non-repetitive blocking voltage	$P_W = 100 \mu s$	800	V
$I_{T(RMS)}$	RMS on-state current	SVxx16LxQ $T_C = 110^\circ C$	16	A
		SVxx16RxQ SVxx16NxQ $T_C = 135^\circ C$	16	
$I_{T(AV)}$	Average on-state current	SVxx16LxQ $T_C = 110^\circ C$	10.2	A
		SVxx16RxQ SVxx16NxQ $T_C = 135^\circ C$	10.2	
I_{TSM}	Peak non-repetitive surge current	single half cycle; $f = 50 Hz$; T_J (initial) = $25^\circ C$	188	A
		single half cycle; $f = 60 Hz$; T_J (initial) = $25^\circ C$	225	
I^2t	I^2t Value for fusing	$t_p = 8.3 ms$	210	A^2s
di/dt	Critical rate of rise of on-state current	$f = 60 Hz$; $T_J = 150^\circ C$	100	$A/\mu s$
I_{GM}	Peak gate current	$T_J = 150^\circ C$	4	A
$P_{G(AV)}$	Average gate power dissipation	$T_J = 150^\circ C$	0.8	W
T_{stg}	Storage temperature range		-40 to 150	$^\circ C$
T_J	Operating junction temperature range		-40 to 150	$^\circ C$

Note: xx=voltage/10, x=sensitivity

Electrical Characteristics ($T_J = 25^\circ C$, unless otherwise specified)

Symbol	Test Conditions	SVxx16x1Q	SVxx16x2Q	Unit
I_{GT}	$V_D = 12V$; $R_L = 60 \Omega$	MIN.	2	mA
		MAX.	6	
V_{GT}		MAX.	1.5	V
dv/dt	$V_D = 67\% V_{DRM}$; gate open; $T_J = 125^\circ C$	MIN.	400	$V/\mu s$
	$V_D = 67\% V_{DRM}$; gate open; $T_J = 150^\circ C$		200	
V_{GD}	$V_D = V_{DRM}$ $R_L = 3.3 k\Omega$ $T_J = 150^\circ C$	MIN.	0.2	V
I_H	$I_T = 200 mA$ (initial)	MAX.	25	40
t_q	$I_T = 2A$; $t_p = 50 \mu s$; $dv/dt = 5V/\mu s$; $di/dt = -30A/\mu s$	MAX.	12	μs
t_{gt}	$I_G = 2 \times I_{GT}$ $P_W = 15 \mu s$ $I_T = 32A$	TYP.	2.6	2.6

Note: xx=voltage/10, x=package

Static Characteristics

Symbol	Test Conditions	Value	Unit
V_{TM}	$I_T = 32A$; $t_p = 380 \mu s$	MAX.	1.7
I_{DRM} / I_{RRM}	$V_{DRM} = V_{RRM}$	$T_J = 25^\circ C$	10
		$T_J = 125^\circ C$	1000
		$T_J = 150^\circ C$	3000

Thermal Resistances

Symbol	Parameter	Value	Unit
$R_{\theta(JC)}$	Junction to case (AC)	SVxx16RxQ	1.0
		SVxx16NxQ	2.5
		SVxx16LxQ	

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Figure 1: Normalized DC Gate Trigger Current vs. Junction Temperature

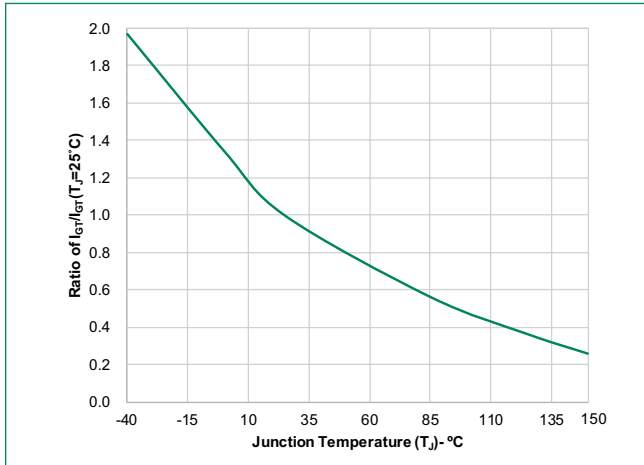


Figure 2: Normalized DC Gate Trigger Voltage vs. Junction Temperature

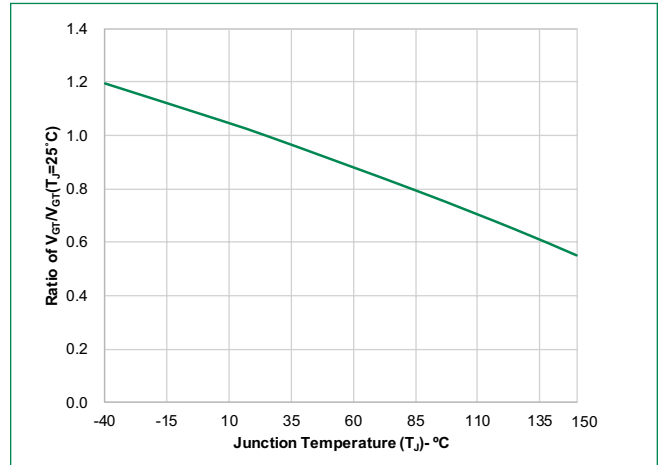


Figure 3: Normalized DC Holding Current vs. Junction Temperature

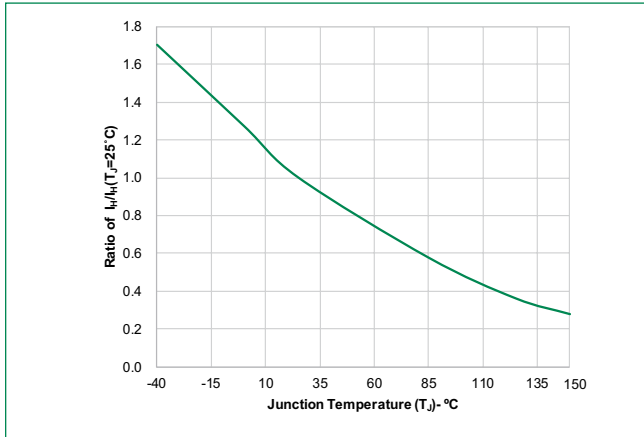


Figure 4: On-State Current vs. On-State Voltage (Typical)

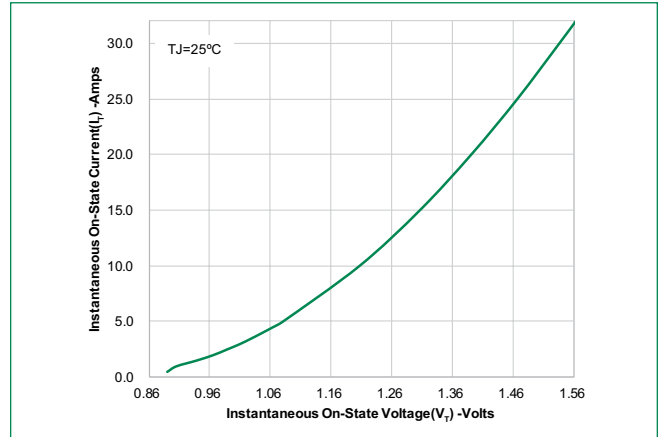


Figure 5: Power Dissipation (Typical) vs. RMS On-State Current

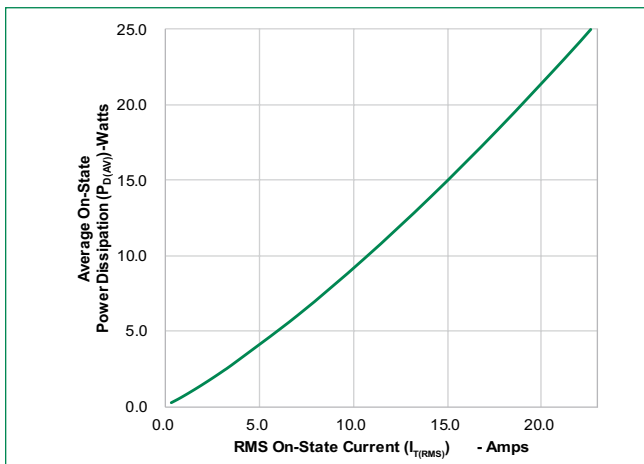
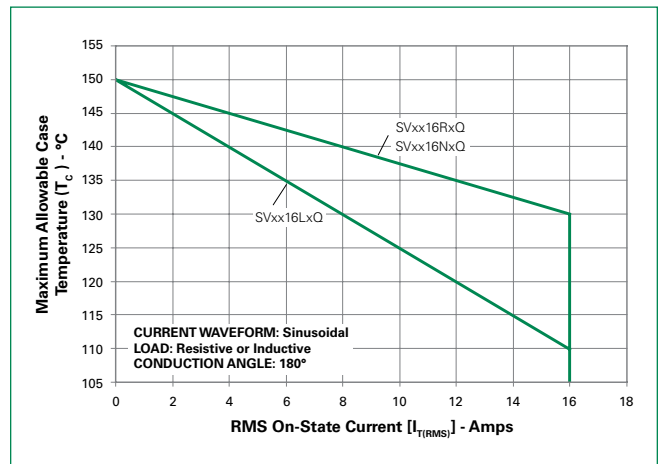


Figure 6: Maximum Allowable Case Temperature vs. RMS On-State Current



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Figure 7: Maximum Allowable Case Temperature vs. Average On-State Current

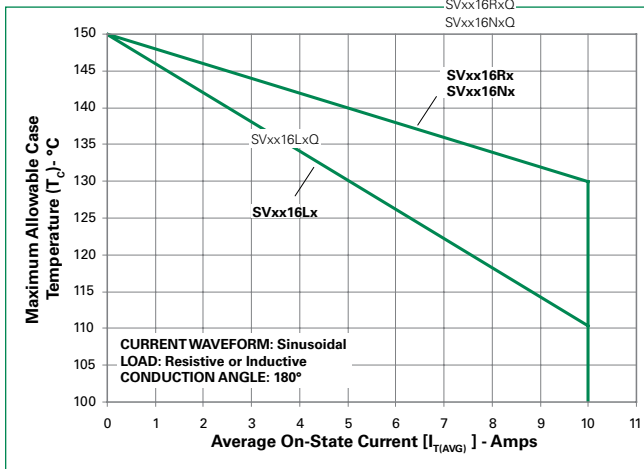


Figure 8: Peak Capacitor Discharge Current

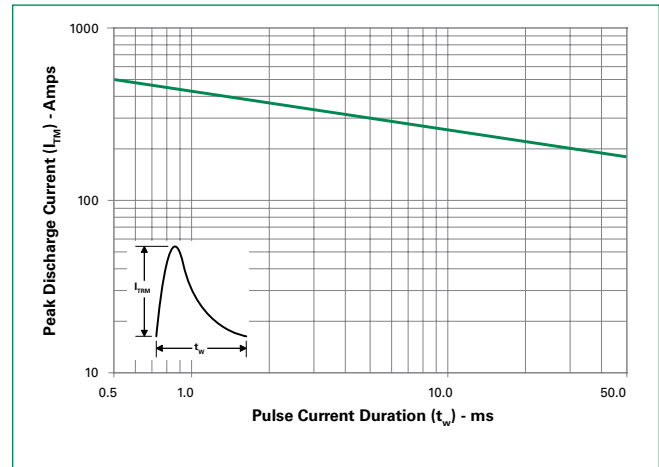


Figure 9: Peak Capacitor Discharge Current Derating

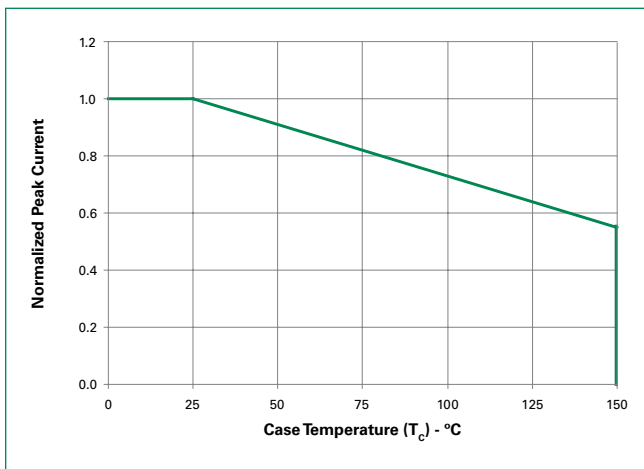
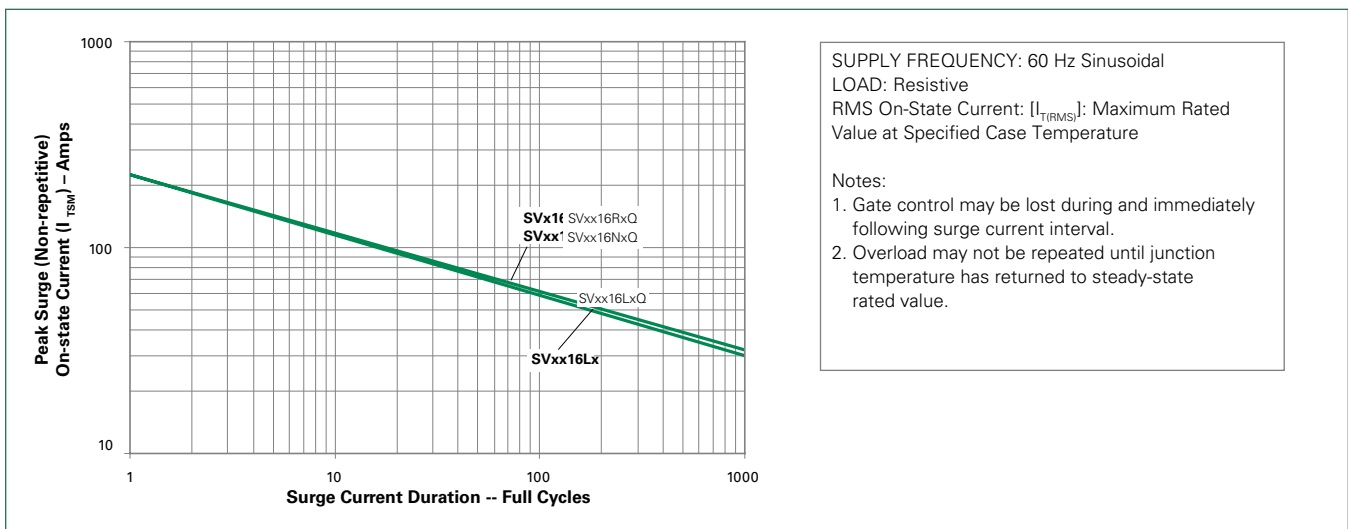


Figure 10: Surge Peak On-State Current vs. Number of Cycles



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Soldering Parameters

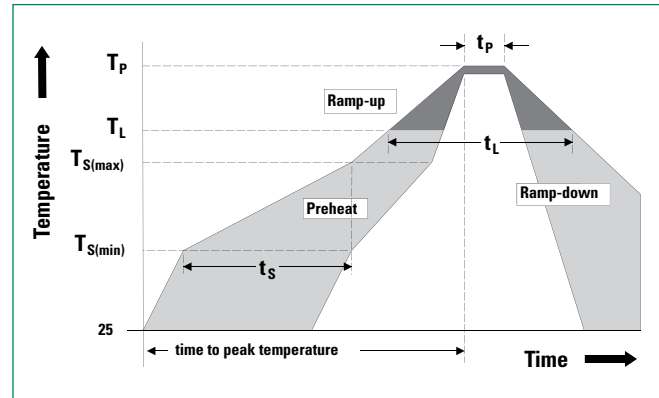
Reflow Condition		Pb – Free assembly
Pre Heat	- Temperature Min ($T_{s(min)}$)	150°C
	- Temperature Max ($T_{s(max)}$)	200°C
	- Time (min to max) (t_s)	60 – 180 secs
Average ramp up rate (Liquidus Temp) (T_L) to peak		5°C/second max
$T_{s(max)}$ to T_L - Ramp-up Rate		5°C/second max
Reflow	- Temperature (T_L) (Liquidus)	217°C
	- Time (t_l)	60 – 150 seconds
Peak Temperature (T_p)		260 ^{+0/-5} °C
Time within 5°C of actual peak Temperature (t_p)		20 – 40 seconds
Ramp-down Rate		5°C/second max
Time 25°C to peak Temperature (T_p)		8 minutes Max.
Do not exceed		280°C

Physical Specifications

Terminal Finish	100% Matte Tin-plated
Body Material	UL Recognized compound meeting flammability rating V-0
Lead Material	Copper Alloy

Design Considerations

Careful selection of the correct component for the application's operating parameters and environment will go a long way toward extending the operating life of the Thyristor. Good design practice should limit the maximum continuous current through the main terminals to 75% of the component rating. Other ways to ensure long life for a power discrete semiconductor are proper heat sinking and selection of voltage ratings for worst case conditions. Overheating, overvoltage (including dv/dt), and surge currents are the main killers of semiconductors. Correct mounting, soldering, and forming of the leads also help protect against component damage.



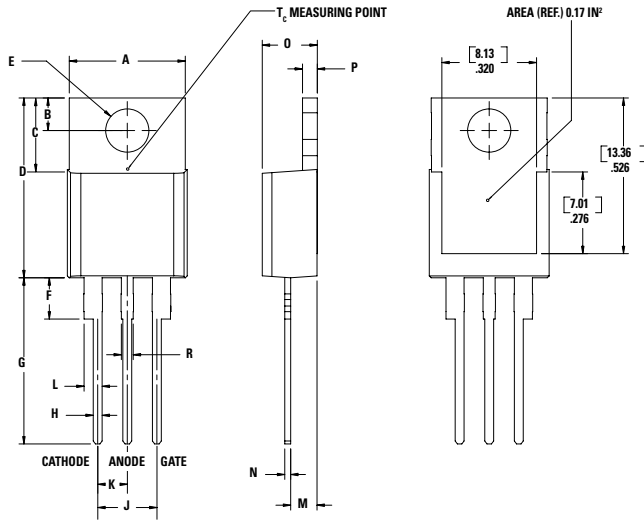
Environmental Specifications

Test	Specifications and Conditions
AC Blocking	MIL-STD-750, M-1040, Cond A Applied Peak AC voltage @ 150°C for 1008 hours
Temperature Cycling	MIL-STD-750, M-1051, 1000 cycles; -55°C to +150°C; 15-min dwell-time
Temperature/Humidity	EIA / JEDEC, JESD22-A101 1008 hours; 160V - DC: 85°C; 85% rel humidity
Resistance to Solder Heat	MIL-STD-750 Method 2031
Solderability	ANSI/J-STD-002, category 3, Test A
Lead Bend	MIL-STD-750, M-2036 Cond E
Moisture Sensitivity Level	Level 1, JEDEC-J-STD-020D

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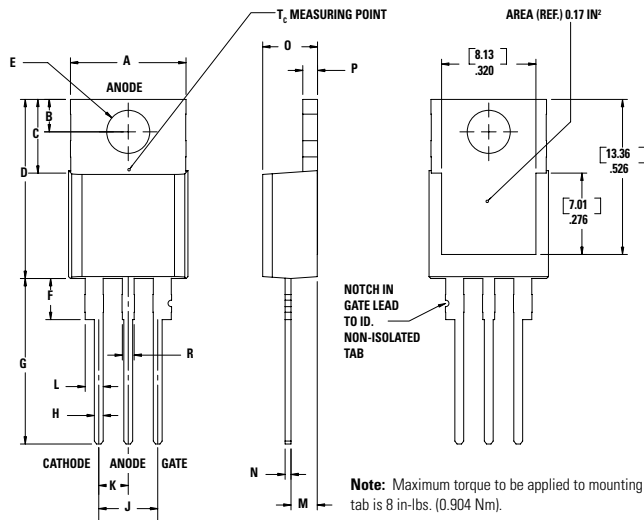
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Dimensions – TO-220AB (L-Package) – Isolated Mounting Tab



Dimension	Inches		Millimeters	
	Min	Max	Min	Max
A	0.380	0.420	9.65	10.67
B	0.105	0.115	2.67	2.92
C	0.230	0.250	5.84	6.35
D	0.590	0.620	14.99	15.75
E	0.142	0.147	3.61	3.73
F	0.110	0.130	2.79	3.30
G	0.540	0.575	13.72	14.61
H	0.025	0.035	0.64	0.89
J	0.195	0.205	4.95	5.21
K	0.095	0.105	2.41	2.67
L	0.060	0.075	1.52	1.91
M	0.085	0.095	2.16	2.41
N	0.018	0.024	0.46	0.61
O	0.178	0.188	4.52	4.78
P	0.045	0.060	1.14	1.52
R	0.038	0.048	0.97	1.22

Dimensions – TO-220AB (R-Package) – Non-Isolated Mounting Tab Common with Center Lead

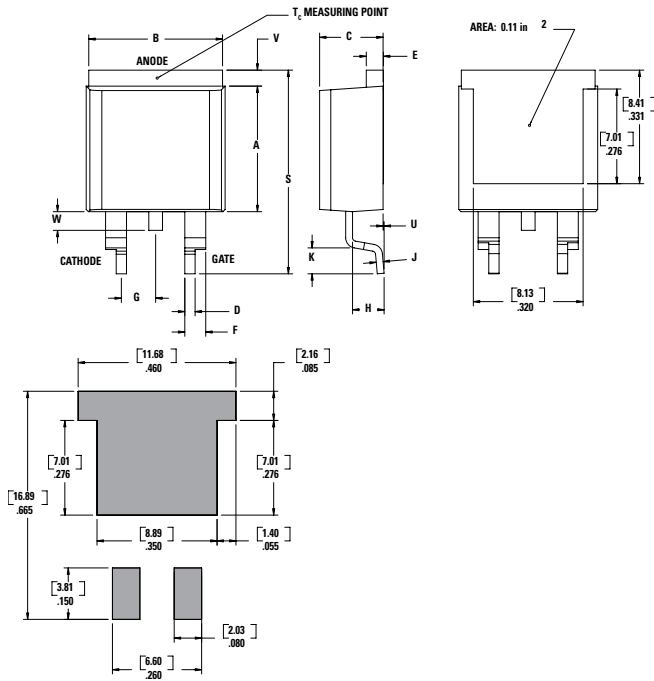


Dimension	Inches		Millimeters	
	Min	Max	Min	Max
A	0.380	0.420	9.65	10.67
B	0.105	0.115	2.67	2.92
C	0.230	0.250	5.84	6.35
D	0.590	0.620	14.99	15.75
E	0.142	0.147	3.61	3.73
F	0.110	0.130	2.79	3.30
G	0.540	0.575	13.72	14.61
H	0.025	0.035	0.64	0.89
J	0.195	0.205	4.95	5.21
K	0.095	0.105	2.41	2.67
L	0.060	0.075	1.52	1.91
M	0.085	0.095	2.16	2.41
N	0.018	0.024	0.46	0.61
O	0.178	0.188	4.52	4.78
P	0.045	0.060	1.14	1.52
R	0.038	0.048	0.97	1.22

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Dimensions – TO- 263AB (N-package) – D2-Pak Surface Mount



Dimension	Inches		Millimeters	
	Min	Max	Min	Max
A	0.360	0.370	9.14	9.40
B	0.380	0.420	9.65	10.67
C	0.178	0.188	4.52	4.78
D	0.025	0.035	0.64	0.89
E	0.045	0.060	1.14	1.52
F	0.060	0.075	1.52	1.91
G	0.095	0.105	2.41	2.67
H	0.092	0.102	2.34	2.59
J	0.018	0.024	0.46	0.61
K	0.090	0.110	2.29	2.79
S	0.590	0.625	14.99	15.88
V	0.035	0.045	0.89	1.14
U	0.002	0.010	0.05	0.25
W	0.040	0.070	1.02	1.78

Product Selector

Part Number	Voltage	Gate Sensitivity	Type	Package
	600V			
SVxx16L1Q	X	6mA	Standard SCR	TO-220L
SVxx16R1Q	X	6mA	Standard SCR	TO-220R
SVxx16N1Q	X	6mA	Standard SCR	TO-263
SVxx16L2Q	X	10mA	Standard SCR	TO-220L
SVxx16R2Q	X	10mA	Standard SCR	TO-220R
SVxx16N2Q	X	10mA	Standard SCR	TO-263

Note: xx = Voltage/10

Packing Options

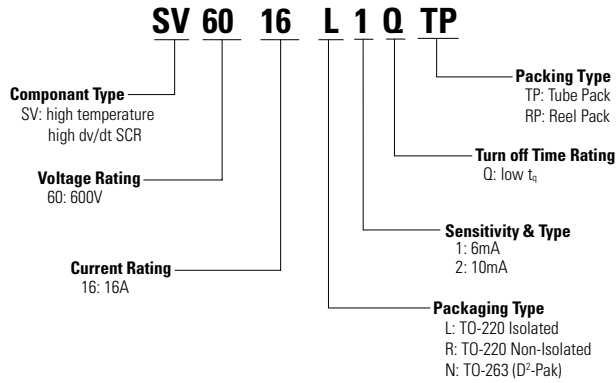
Part Number	Marking	Weight	Packing Mode	Base Quantity
SVxx16LxQTP	SVxx16LxQ	2.2g	Tube	1000 (50 per tube)
SVxx16RxQTP	SVxx16RxQ	2.2g	Tube	1000 (50 per tube)
SVxx16NxQTP	SVxx16NxQ	1.6g	Tube	1000 (50 per tube)
SVxx16NxQRP	SVxx16NxQ	1.6g	Embossed Carrier	500

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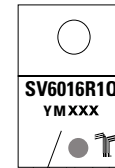
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Part Numbering System



Part Marking System

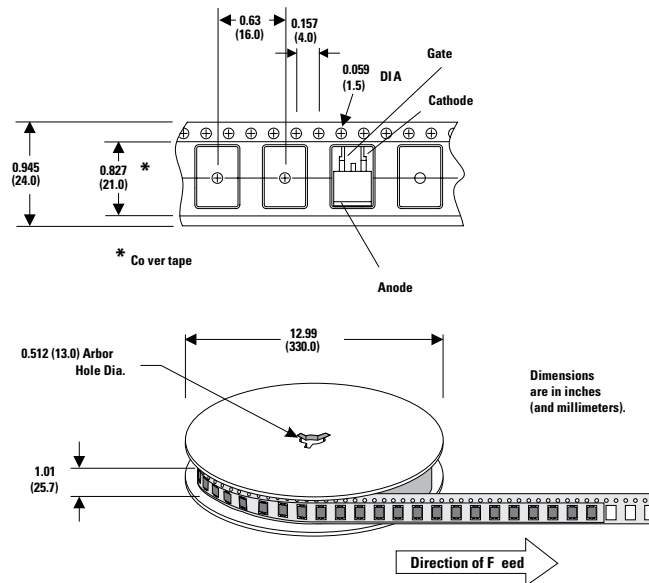
T0-220 AB - (L and R Package)
T0-263 AB - (N Package)



Date Code Marking
Y: Year Code
M: Month Code
XXX: Lot Trace Code

TO-263 Embossed Carrier Reel Pack (RP) Specifications

Meets all EIA-481-2 Standards



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